

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A ~~thin film integrated circuit~~ semiconductor device ~~comprising: comprising a thin film integrated circuit,~~
wherein the thin film integrated circuit comprises:
a substrate;
an adhesive over the substrate;
a metal oxide over the adhesive;
an insulating film over the metal oxide;
a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film; and
~~a thin film integrated circuit having the semiconductor film, the gate insulating film, and the gate electrode.~~
2. (Currently Amended) A ~~thin film integrated circuit~~ semiconductor device according to claim 1, wherein the metal oxide comprises WO₂ or WO₃.
3. (Currently Amended) A ~~thin film integrated circuit~~ semiconductor device according to claim 1, wherein the metal oxide is an oxide of an element selected from the group consisting of W, Ti, Ta, Mo, Nd, Ni, Co, Zr, Zn, Ru, Rh, Pd, Os, and Ir; an alloy containing the metal as a main component; or a chemical compound thereof.
4. (Currently Amended) A ~~thin film integrated circuit~~ semiconductor device according to claim 1, wherein the semiconductor film functions as an active region.

5. (Currently Amended) A ~~thin film integrated circuit~~ semiconductor device according to claim 1, wherein the semiconductor film functions as a channel region.

6. (Currently Amended) An IC label ~~comprising:~~ comprising a thin film integrated circuit,

wherein the thin film integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film; ~~and~~

~~a thin film integrated circuit having the semiconductor film, the gate insulating film, and the gate electrode.~~

7. (Original) An IC label according to claim 6, wherein the IC label is a contactless type.

8. (Previously Presented) An IC label according to claim 6, wherein a surface of the IC label can be printed with a character, a letter, text, a symbol, or a diagram.

9. (Currently Amended) An IC label comprising a contactless thin film integrated circuit,

wherein the thin film integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a semiconductor film provided over the insulating film;
a gate electrode provided over the semiconductor film with a gate insulating film interposed between the semiconductor layer and the gate electrode; and
an antenna in a same layer as the gate electrode.

10. (Original) An IC label according to claim 9, wherein the antenna is formed from a same material as the gate electrode.

11. (Original) An IC label according to claim 9, wherein the antenna comprises a conductive paste.

12. (Currently Amended) An IC label comprising a contactless thin film integrated circuit,

wherein the thin film integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a semiconductor film, a gate insulating film, and a gate electrode which are provided over the insulating film;

a wiring connected to an impurity region of the semiconductor film; and

an antenna in a same layer as the wiring.

13. (Previously Presented) An IC label according to claim 12, wherein the antenna comprises a same material as the wiring.

14. (Original) An IC label according to claim 12, wherein the antenna comprises a conductive paste.

15. (Currently Amended) A container ~~comprising:~~ comprising a thin film integrated circuit,

wherein the thin film integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a semiconductor film, a gate insulating film, and a gate electrode, which are provided over the insulating film; and

~~a thin film integrated circuit having the semiconductor film, the gate insulating film, and the gate electrode,~~

~~wherein the thin film integrated circuit is adhered to the container.~~

16. (Original) A container according to claim 15, wherein the thin film integrated circuit is covered by a label.

17. (Original) A container according to claim 16, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

18. (Original) A container according to claim 15, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

19. (Previously Presented) A container according to claim 15,
wherein the metal oxide is adhered to the container.

20. (Currently Amended) A container comprising a contactless thin film integrated circuit,

wherein the thin film integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

a semiconductor film provided over the insulating film;

a gate electrode that is provided over the semiconductor film; and

an antenna that is provided in a same layer as the gate electrode.

21. (Original) A container according to claim 20, wherein the thin film integrated circuit is covered by a label.

22. (Original) A container according to claim 21, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

23. (Original) A container according to claim 20, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

24. (Currently Amended) A container comprising a contactless thin film integrated circuit,

wherein the thin film integrated circuit comprises:

a substrate;

an adhesive over the substrate;

a metal oxide over the adhesive;

an insulating film over the metal oxide;

~~wherein the thin film integrated circuit comprises:~~

a semiconductor film, a gate insulating film, and a gate electrode which are provided over ~~one surface of an~~ the insulating film;

a wiring provided over the semiconductor film; and

an antenna provided in a same layer as the wiring.

25. (Original) A container according to claim 24, wherein the thin film integrated circuit is covered by a label.

26. (Original) A container according to claim 25, wherein a protective film having a DLC film or a CN film is provided between the thin film integrated circuit and the label.

27. (Original) A container according to claim 24, wherein the thin film integrated circuit is held between a first label and a second label, and the second label is affixed to the thin film integrated circuit with an adhesive agent.

28.-60. (Canceled)